PCN Number: 20200206012 PCN		PCN Date:	Feb. 18, 2020		
Title: Datasheet for BQ25910					
Customer Contact:	PCN Manager		Dept:	Quality Services	
Change Type:			-		
Assembly Site	Des	ign	Wafer	<sup>-</sup> Bump Site	
Assembly Process		Sheet		- Bump Material	
Assembly Materials	; 🗌 Part	number change	Wafer	- Bump Process	
Mechanical Specific	cation 📃 Test	: Site	Wafer	<sup>-</sup> Fab Site	
Packing/Shipping/L	abeling 📃 Test	Process	Wafer	- Fab Materials	
			Wafer	- Fab Process	
Notification Details					
Description of Change:					
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.					
SLVSDU0B – SEPTEMBER 2017 – REVISED SEPTEMBER 2019					
Changes from Revision A (February 2018) to Revision B Page					
Changed t <sub>BAT_LOWV_DGL</sub> from 20 ms to 170 ms in Timing Requirements section					
Changed DEV_REV default value from 0b001 to 0b010 in REG0D register Part Information Register (Address = Dh) [reset = 0Ah] 42					
The datasheet number	will be changing.		1		
Device Family		Change From:	Chang	е То:	
BQ25910		SLVSDU0A	SLVSD	UOB	
These changes may be	reviewed at the data	asheet links provided	d.		
http://www.ti.com/product/BQ25910					
Reason for Change:					
To accurately reflect device characteristics.					
Anticipated impact of	n Fit, Form, Functi	on, Quality or Reli	ability (pos	itive / negative):	
No anticipated impact. To the actual device.	This is a specification	n change announcer	nent only. Th	ere are no changes	
Changes to product i	dentification resul	ting from this PCN	:		
None.					
Product Affected:					
	BODEO 1 OVERT				
BQ25910YFFR	BQ25910YFFT				
For questions regarding your local Field Sales R		can be sent to the i	regional conta	acts shown below or	

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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